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Understanding Embedded - CPLDs (Complex Programmable Logic Devices)

Embedded - CPLDs, or Complex Programmable Logic Devices, are highly versatile digital logic devices used in electronic systems. These programmable components are designed to perform complex logical operations and can be customized for specific applications. Unlike fixed-function ICs, CPLDs offer the flexibility to reprogram their configuration, making them an ideal choice for various embedded systems. They consist of a set of logic gates and programmable interconnects, allowing designers to implement complex logic circuits without needing custom hardware.

Applications of Embedded - CPLDs

Details	
Product Status	Obsolete
Programmable Type	In System Programmable
Delay Time tpd(1) Max	7.5 ns
Voltage Supply - Internal	3V ~ 3.6V
Number of Logic Elements/Blocks	8
Number of Macrocells	128
Number of Gates	2500
Number of I/O	100
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	256-BGA
Supplier Device Package	256-FBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/intel/epm7128aefc256-7

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

- Software design support and automatic place-and-route provided by Altera's development systems for Windows-based PCs and Sun SPARCstation, and HP 9000 Series 700/800 workstations
- Additional design entry and simulation support provided by EDIF 2 0 0 and 3 0 0 netlist files, library of parameterized modules (LPM), Verilog HDL, VHDL, and other interfaces to popular EDA tools from manufacturers such as Cadence, Exemplar Logic, Mentor Graphics, OrCAD, Synopsys, Synplicity, and VeriBest
- Programming support with Altera's Master Programming Unit (MPU), MasterBlaster™ serial/universal serial bus (USB) communications cable, ByteBlasterMV™ parallel port download cable, and BitBlaster™ serial download cable, as well as programming hardware from third-party manufacturers and any Jam™ STAPL File (.jam), Jam Byte-Code File (.jbc), or Serial Vector Format File- (.svf) capable in-circuit tester

General Description

MAX 7000A (including MAX 7000AE) devices are high-density, high-performance devices based on Altera's second-generation MAX architecture. Fabricated with advanced CMOS technology, the EEPROM-based MAX 7000A devices operate with a 3.3-V supply voltage and provide 600 to 10,000 usable gates, ISP, pin-to-pin delays as fast as 4.5 ns, and counter speeds of up to 227.3 MHz. MAX 7000A devices in the -4, -5, -6, -7, and some -10 speed grades are compatible with the timing requirements for 33 MHz operation of the PCI Special Interest Group (PCI SIG) *PCI Local Bus Specification, Revision 2.2.* See Table 2.

Device			Speed	Grade		
	-4	-5	-6	-7	-10	-12
EPM7032AE	✓			✓	✓	
EPM7064AE	✓			✓	✓	
EPM7128A			✓	✓	✓	✓
EPM7128AE		✓		✓	✓	
EPM7256A			✓	✓	✓	✓
EPM7256AE		✓		✓	✓	
EPM7512AE				✓	✓	✓

MAX 7000A devices use CMOS EEPROM cells to implement logic functions. The user-configurable MAX 7000A architecture accommodates a variety of independent combinatorial and sequential logic functions. The devices can be reprogrammed for quick and efficient iterations during design development and debug cycles, and can be programmed and erased up to 100 times.

MAX 7000A devices contain from 32 to 512 macrocells that are combined into groups of 16 macrocells, called logic array blocks (LABs). Each macrocell has a programmable-AND/fixed-OR array and a configurable register with independently programmable clock, clock enable, clear, and preset functions. To build complex logic functions, each macrocell can be supplemented with both shareable expander product terms and high-speed parallel expander product terms, providing up to 32 product terms per macrocell.

MAX 7000A devices provide programmable speed/power optimization. Speed-critical portions of a design can run at high speed/full power, while the remaining portions run at reduced speed/low power. This speed/power optimization feature enables the designer to configure one or more macrocells to operate at 50% or lower power while adding only a nominal timing delay. MAX 7000A devices also provide an option that reduces the slew rate of the output buffers, minimizing noise transients when non-speed-critical signals are switching. The output drivers of all MAX 7000A devices can be set for 2.5 V or 3.3 V, and all input pins are 2.5-V, 3.3-V, and 5.0-V tolerant, allowing MAX 7000A devices to be used in mixed-voltage systems.

MAX 7000A devices are supported by Altera development systems, which are integrated packages that offer schematic, text—including VHDL, Verilog HDL, and the Altera Hardware Description Language (AHDL)—and waveform design entry, compilation and logic synthesis, simulation and timing analysis, and device programming. The software provides EDIF 2 0 0 and 3 0 0, LPM, VHDL, Verilog HDL, and other interfaces for additional design entry and simulation support from other industry-standard PC- and UNIX-workstation-based EDA tools. The software runs on Windows-based PCs, as well as Sun SPARCstation, and HP 9000 Series 700/800 workstations.



For more information on development tools, see the MAX+PLUS II Programmable Logic Development System & Software Data Sheet and the Quartus Programmable Logic Development System & Software Data Sheet.

Functional Description

The MAX 7000A architecture includes the following elements:

- Logic array blocks (LABs)
- Macrocells
- Expander product terms (shareable and parallel)
- Programmable interconnect array
- I/O control blocks

The MAX 7000A architecture includes four dedicated inputs that can be used as general-purpose inputs or as high-speed, global control signals (clock, clear, and two output enable signals) for each macrocell and I/O pin. Figure 1 shows the architecture of MAX 7000A devices.

For registered functions, each macrocell flipflop can be individually programmed to implement D, T, JK, or SR operation with programmable clock control. The flipflop can be bypassed for combinatorial operation. During design entry, the designer specifies the desired flipflop type; the Altera software then selects the most efficient flipflop operation for each registered function to optimize resource utilization.

Each programmable register can be clocked in three different modes:

- Global clock signal. This mode achieves the fastest clock-to-output performance.
- Global clock signal enabled by an active-high clock enable. A clock enable is generated by a product term. This mode provides an enable on each flipflop while still achieving the fast clock-to-output performance of the global clock.
- Array clock implemented with a product term. In this mode, the flipflop can be clocked by signals from buried macrocells or I/O pins.

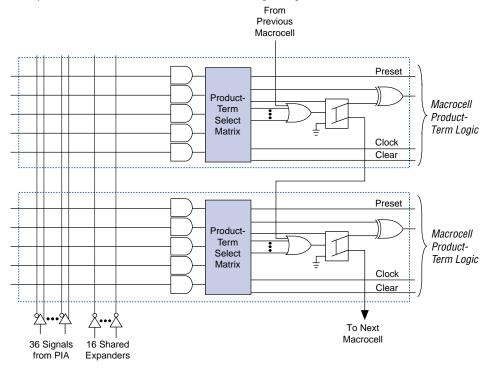
Two global clock signals are available in MAX 7000A devices. As shown in Figure 1, these global clock signals can be the true or the complement of either of the global clock pins, GCLK1 or GCLK2.

Each register also supports asynchronous preset and clear functions. As shown in Figure 2, the product-term select matrix allocates product terms to control these operations. Although the product-term-driven preset and clear from the register are active high, active-low control can be obtained by inverting the signal within the logic array. In addition, each register clear function can be individually driven by the active-low dedicated global clear pin (GCLRn). Upon power-up, each register in a MAX 7000AE device may be set to either a high or low state. This power-up state is specified at design entry. Upon power-up, each register in EPM7128A and EPM7256A devices are set to a low state.

All MAX 7000A I/O pins have a fast input path to a macrocell register. This dedicated path allows a signal to bypass the PIA and combinatorial logic and be clocked to an input D flipflop with an extremely fast (as low as 2.5 ns) input setup time.

Figure 4. MAX 7000A Parallel Expanders

Unused product terms in a macrocell can be allocated to a neighboring macrocell.



Programmable Interconnect Array

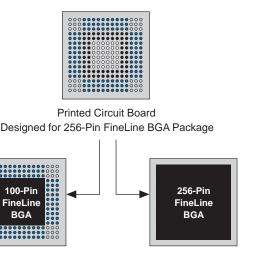
Logic is routed between LABs on the PIA. This global bus is a programmable path that connects any signal source to any destination on the device. All MAX 7000A dedicated inputs, I/O pins, and macrocell outputs feed the PIA, which makes the signals available throughout the entire device. Only the signals required by each LAB are actually routed from the PIA into the LAB. Figure 5 shows how the PIA signals are routed into the LAB. An EEPROM cell controls one input to a 2-input AND gate, which selects a PIA signal to drive into the LAB.

SameFrame Pin-Outs

MAX 7000A devices support the SameFrame pin-out feature for FineLine BGA packages. The SameFrame pin-out feature is the arrangement of balls on FineLine BGA packages such that the lower-ball-count packages form a subset of the higher-ball-count packages. SameFrame pin-outs provide the flexibility to migrate not only from device to device within the same package, but also from one package to another. A given printed circuit board (PCB) layout can support multiple device density/package combinations. For example, a single board layout can support a range of devices from an EPM7128AE device in a 100-pin FineLine BGA package to an EPM7512AE device in a 256-pin FineLine BGA package.

The Altera design software provides support to design PCBs with SameFrame pin-out devices. Devices can be defined for present and future use. The software generates pin-outs describing how to lay out a board to take advantage of this migration (see Figure 7).

Figure 7. SameFrame Pin-Out Example



100-Pin FineLine BGA Package (Reduced I/O Count or Logic Requirements)

256-Pin FineLine BGA Package (Increased I/O Count or Logic Requirements)

Programming Times

The time required to implement each of the six programming stages can be broken into the following two elements:

- A pulse time to erase, program, or read the EEPROM cells.
- A shifting time based on the test clock (TCK) frequency and the number of TCK cycles to shift instructions, address, and data into the device.

By combining the pulse and shift times for each of the programming stages, the program or verify time can be derived as a function of the TCK frequency, the number of devices, and specific target device(s). Because different ISP-capable devices have a different number of EEPROM cells, both the total fixed and total variable times are unique for a single device.

Programming a Single MAX 7000A Device

The time required to program a single MAX 7000A device in-system can be calculated from the following formula:

$$t_{PROG} = t_{PPULSE} + \frac{Cycle_{PTCK}}{f_{TCK}}$$

where: t_{PROG} = Programming time t_{PPULSE} = Sum of the fixed times to erase, program, and

verify the EEPROM cells

 $Cycle_{PTCK}$ = Number of TCK cycles to program a device

= TCK frequency

The ISP times for a stand-alone verification of a single MAX 7000A device can be calculated from the following formula:

$$t_{VER} = t_{VPULSE} + \frac{Cycle_{VTCK}}{f_{TCK}}$$

where: t_{VER} = Verify time

 t_{VPULSE} = Sum of the fixed times to verify the EEPROM cells

 $Cycle_{VTCK}$ = Number of TCK cycles to verify a device

The programming times described in Tables 5 through 7 are associated with the worst-case method using the enhanced ISP algorithm.

Device	Progra	mming	Stand-Alone Verification			
	t _{PPULSE} (s)	Cycle _{PTCK}	t _{VPULSE} (s)	Cycle _{VTCK}		
EPM7032AE	2.00	55,000	0.002	18,000		
EPM7064AE	2.00	105,000	0.002	35,000		
EPM7128AE	2.00	205,000	0.002	68,000		
EPM7256AE	2.00	447,000	0.002	149,000		
EPM7512AE	2.00	890,000	0.002	297,000		
EPM7128A (1)	5.11	832,000	0.03	528,000		
EPM7256A (1)	6.43	1,603,000	0.03	1,024,000		

Tables 6 and 7 show the in-system programming and stand alone verification times for several common test clock frequencies.

Device				1	TCK				Units
	10 MHz	5 MHz	2 MHz	1 MHz	500 kHz	200 kHz	100 kHz	50 kHz	
EPM7032AE	2.01	2.01	2.03	2.06	2.11	2.28	2.55	3.10	s
EPM7064AE	2.01	2.02	2.05	2.11	2.21	2.53	3.05	4.10	S
EPM7128AE	2.02	2.04	2.10	2.21	2.41	3.03	4.05	6.10	S
EPM7256AE	2.05	2.09	2.23	2.45	2.90	4.24	6.47	10.94	S
EPM7512AE	2.09	2.18	2.45	2.89	3.78	6.45	10.90	19.80	S
EPM7128A (1)	5.19	5.27	5.52	5.94	6.77	9.27	13.43	21.75	S
EPM7256A (1)	6.59	6.75	7.23	8.03	9.64	14.45	22.46	38.49	S

Table 7. MAX 70	AX 7000A Stand-Alone Verification Times for Different Test Clock Frequencies											
Device				f	TCK				Units			
	10 MHz	5 MHz	2 MHz	1 MHz	500 kHz	200 kHz	100 kHz	50 kHz				
EPM7032AE	0.00	0.01	0.01	0.02	0.04	0.09	0.18	0.36	s			
EPM7064AE	0.01	0.01	0.02	0.04	0.07	0.18	0.35	0.70	S			
EPM7128AE	0.01	0.02	0.04	0.07	0.14	0.34	0.68	1.36	S			
EPM7256AE	0.02	0.03	0.08	0.15	0.30	0.75	1.49	2.98	S			
EPM7512AE	0.03	0.06	0.15	0.30	0.60	1.49	2.97	5.94	S			
EPM7128A (1)	0.08	0.14	0.29	0.56	1.09	2.67	5.31	10.59	S			
EPM7256A (1)	0.13	0.24	0.54	1.06	2.08	5.15	10.27	20.51	S			

Note to tables:

(1) EPM7128A and EPM7256A devices can only be programmed with an adaptive algorithm; users programming these two devices on platforms that cannot use an adaptive algorithm should use EPM7128AE and EPM7256AE devices.

Programming with External Hardware

MAX 7000A devices can be programmed on Windows-based PCs with an Altera Logic Programmer card, the MPU, and the appropriate device adapter. The MPU performs continuity checks to ensure adequate electrical contact between the adapter and the device.



For more information, see the *Altera Programming Hardware Data Sheet*.

The Altera software can use text- or waveform-format test vectors created with the Altera Text Editor or Waveform Editor to test the programmed device. For added design verification, designers can perform functional testing to compare the functional device behavior with the results of simulation.

Data I/O, BP Microsystems, and other programming hardware manufacturers provide programming support for Altera devices.



For more information, see *Programming Hardware Manufacturers*.

IEEE Std. 1149.1 (JTAG) Boundary-Scan Support

MAX 7000A devices include the JTAG BST circuitry defined by IEEE Std. 1149.1. Table 8 describes the JTAG instructions supported by MAX 7000A devices. The pin-out tables, available from the Altera web site (http://www.altera.com), show the location of the JTAG control pins for each device. If the JTAG interface is not required, the JTAG pins are available as user I/O pins.

Open-Drain Output Option

MAX 7000A devices provide an optional open-drain (equivalent to open-collector) output for each I/O pin. This open-drain output enables the device to provide system-level control signals (e.g., interrupt and write enable signals) that can be asserted by any of several devices. This output can also provide an additional wired-OR plane.

Open-drain output pins on MAX 7000A devices (with a pull-up resistor to the 5.0-V supply) can drive 5.0-V CMOS input pins that require a high $V_{IH}.$ When the open-drain pin is active, it will drive low. When the pin is inactive, the resistor will pull up the trace to 5.0 V to meet CMOS V_{OH} requirements. The open-drain pin will only drive low or tri-state; it will never drive high. The rise time is dependent on the value of the pull-up resistor and load impedance. The I_{OL} current specification should be considered when selecting a pull-up resistor.

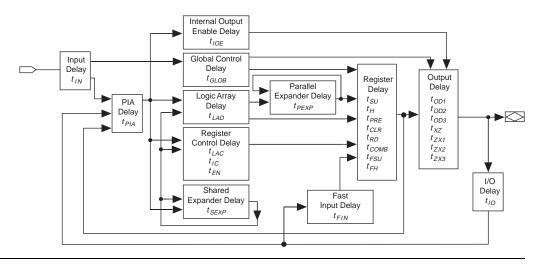
Programmable Ground Pins

Each unused I/O pin on MAX 7000A devices may be used as an additional ground pin. In EPM7128A and EPM7256A devices, utilizing unused I/O pins as additional ground pins requires using the associated macrocell. In MAX 7000AE devices, this programmable ground feature does not require the use of the associated macrocell; therefore, the buried macrocell is still available for user logic.

Slew-Rate Control

The output buffer for each MAX 7000A I/O pin has an adjustable output slew rate that can be configured for low-noise or high-speed performance. A faster slew rate provides high-speed transitions for high-performance systems. However, these fast transitions may introduce noise transients into the system. A slow slew rate reduces system noise, but adds a nominal delay of 4 to 5 ns. When the configuration cell is turned off, the slew rate is set for low-noise performance. Each I/O pin has an individual EEPROM bit that controls the slew rate, allowing designers to specify the slew rate on a pin-by-pin basis. The slew rate control affects both the rising and falling edges of the output signal.

Figure 11. MAX 7000A Timing Model

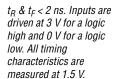


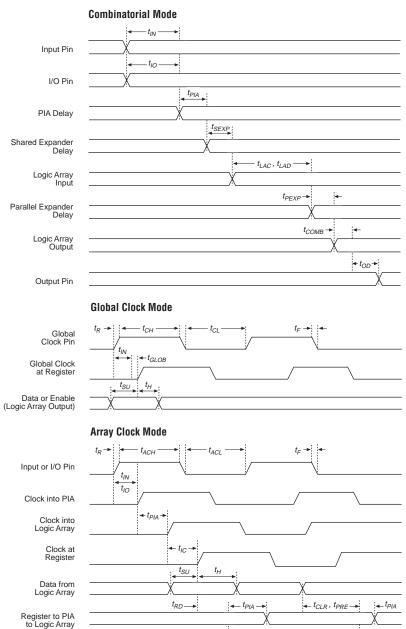
The timing characteristics of any signal path can be derived from the timing model and parameters of a particular device. External timing parameters, which represent pin-to-pin timing delays, can be calculated as the sum of internal parameters. Figure 12 shows the timing relationship between internal and external delay parameters.



See Application Note 94 (Understanding MAX 7000 Timing) for more information.

Figure 12. MAX 7000A Switching Waveforms





 $-t_{OD}$

← t_{OD} -

Altera Corporation 33

Register Output to Pin

Symbol	Parameter	Conditions			Speed	Grade			Unit
			-	4		-7		10	
			Min	Max	Min	Max	Min	Max	
t _{IN}	Input pad and buffer delay			0.6		1.1		1.4	ns
t _{IO}	I/O input pad and buffer delay			0.6		1.1		1.4	ns
t _{FIN}	Fast input delay			2.5		3.0		3.7	ns
t _{SEXP}	Shared expander delay			1.8		3.0		3.9	ns
t_{PEXP}	Parallel expander delay			0.4		0.7		0.9	ns
t_{LAD}	Logic array delay			1.5		2.5		3.2	ns
t _{LAC}	Logic control array delay			0.6		1.0		1.2	ns
t _{IOE}	Internal output enable delay			0.0		0.0		0.0	ns
t _{OD1}	Output buffer and pad delay, slow slew rate = off V _{CCIO} = 3.3 V	C1 = 35 pF		0.8		1.3		1.8	ns
t _{OD2}	Output buffer and pad delay, slow slew rate = off V _{CCIO} = 2.5 V	C1 = 35 pF (5)		1.3		1.8		2.3	ns
t _{OD3}	Output buffer and pad delay, slow slew rate = on V _{CCIO} = 2.5 V or 3.3 V	C1 = 35 pF		5.8		6.3		6.8	ns
t _{ZX1}	Output buffer enable delay, slow slew rate = off $V_{CCIO} = 3.3 \text{ V}$	C1 = 35 pF		4.0		4.0		5.0	ns
t _{ZX2}	Output buffer enable delay, slow slew rate = off $V_{CCIO} = 2.5 \text{ V}$	C1 = 35 pF (5)		4.5		4.5		5.5	ns
t _{ZX3}	Output buffer enable delay, slow slew rate = on V _{CCIO} = 3.3 V	C1 = 35 pF		9.0		9.0		10.0	ns
t_{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		4.0		5.0	ns
t _{SU}	Register setup time		1.3		2.0		2.9		ns
t _H	Register hold time		0.6		1.0		1.3		ns
t _{FSU}	Register setup time of fast input		1.0		1.5		1.5		ns
t _{FH}	Register hold time of fast input		1.5		1.5		1.5		ns
t_{RD}	Register delay			0.7		1.2		1.6	ns
t _{COMB}	Combinatorial delay			0.6		0.9		1.3	ns
t _{IC}	Array clock delay			1.2		1.9		2.5	ns

Symbol	Parameter	Conditions			Speed	Grade			Unit
			-:	5	-	7	-1	10	
			Min	Max	Min	Max	Min	Max	
t _{PD1}	Input to non- registered output	C1 = 35 pF (2)		5.0		7.5		10	ns
t _{PD2}	I/O input to non- registered output	C1 = 35 pF (2)		5.0		7.5		10	ns
t _{SU}	Global clock setup time	(2)	3.3		4.9		6.6		ns
t _H	Global clock hold time	(2)	0.0		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input		2.5		3.0		3.0		ns
t _{FH}	Global clock hold time of fast input		0.0		0.0		0.0		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF	1.0	3.4	1.0	5.0	1.0	6.6	ns
t _{CH}	Global clock high time		2.0		3.0		4.0		ns
t _{CL}	Global clock low time		2.0		3.0		4.0		ns
t _{ASU}	Array clock setup time	(2)	1.8		2.8		3.8		ns
t _{AH}	Array clock hold time	(2)	0.2		0.3		0.4		ns
t _{ACO1}	Array clock to output delay	C1 = 35 pF (2)	1.0	4.9	1.0	7.1	1.0	9.4	ns
t _{ACH}	Array clock high time		2.0		3.0		4.0		ns
t _{ACL}	Array clock low time		2.0		3.0		4.0		ns
t _{CPPW}	Minimum pulse width for clear and preset	(3)	2.0		3.0		4.0		ns
t _{CNT}	Minimum global clock period	(2)		5.2		7.7		10.2	ns
f _{CNT}	Maximum internal global clock frequency	(2), (4)	192.3		129.9		98.0		MHz
t _{ACNT}	Minimum array clock period	(2)		5.2		7.7		10.2	ns
f _{ACNT}	Maximum internal array clock frequency	(2), (4)	192.3		129.9		98.0		MHz

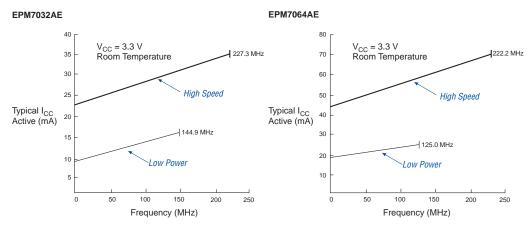
Symbol	Parameter	Conditions			Speed	Grade			Unit
		·	-!	5	-	7	-1	10	
			Min	Max	Min	Max	Min	Max	
t _{PD1}	Input to non- registered output	C1 = 35 pF (2)		5.5		7.5		10	ns
t _{PD2}	I/O input to non- registered output	C1 = 35 pF (2)		5.5		7.5		10	ns
t _{SU}	Global clock setup time	(2)	3.9		5.2		6.9		ns
t _H	Global clock hold time	(2)	0.0		0.0		0.0		ns
t _{FSU}	Global clock setup time of fast input		2.5		3.0		3.0		ns
t _{FH}	Global clock hold time of fast input		0.0		0.0		0.0		ns
t _{CO1}	Global clock to output delay	C1 = 35 pF	1.0	3.5	1.0	4.8	1.0	6.4	ns
t _{CH}	Global clock high time		2.0		3.0		4.0		ns
t _{CL}	Global clock low time		2.0		3.0		4.0		ns
t _{ASU}	Array clock setup time	(2)	2.0		2.7		3.6		ns
t _{AH}	Array clock hold time	(2)	0.2		0.3		0.5		ns
t _{ACO1}	Array clock to output delay	C1 = 35 pF (2)	1.0	5.4	1.0	7.3	1.0	9.7	ns
t _{ACH}	Array clock high time		2.0		3.0		4.0		ns
t _{ACL}	Array clock low time		2.0		3.0		4.0		ns
t _{CPPW}	Minimum pulse width for clear and preset	(3)	2.0		3.0		4.0		ns
t _{CNT}	Minimum global clock period	(2)		5.8		7.9		10.5	ns
f _{CNT}	Maximum internal global clock frequency	(2), (4)	172.4		126.6		95.2		MHz
t _{ACNT}	Minimum array clock period	(2)		5.8		7.9		10.5	ns
f _{ACNT}	Maximum internal array clock frequency	(2), (4)	172.4		126.6		95.2		MHz

Symbol	Parameter	Conditions	Speed Grade							
			_	7		10		12		
			Min	Max	Min	Max	Min	Max		
t _{IC}	Array clock delay			1.8		2.3		2.9	ns	
t _{EN}	Register enable time			1.0		1.3		1.7	ns	
t_{GLOB}	Global control delay			1.7		2.2		2.7	ns	
t _{PRE}	Register preset time			1.0		1.4		1.7	ns	
t _{CLR}	Register clear time			1.0		1.4		1.7	ns	
t_{PIA}	PIA delay	(2)		3.0		4.0		4.8	ns	
t_{LPA}	Low-power adder	(6)		4.5		5.0		5.0	ns	

Symbol	Parameter	Conditions				Speed	Grade				Unit
			-	6	-	7	-1	10	-1	12	
			Min	Max	Min	Max	Min	Max	Min	Max	
t _{IN}	Input pad and buffer delay			0.6		0.7		0.9		1.1	ns
t_{IO}	I/O input pad and buffer delay			0.6		0.7		0.9		1.1	ns
t _{FIN}	Fast input delay			2.7		3.1		3.6		3.9	ns
t _{SEXP}	Shared expander delay			2.5		3.2		4.3		5.1	ns
t _{PEXP}	Parallel expander delay			0.7		0.8		1.1		1.3	ns
t _{LAD}	Logic array delay			2.4		3.0		4.1		4.9	ns
t _{LAC}	Logic control array delay			2.4		3.0		4.1		4.9	ns
t _{IOE}	Internal output enable delay			0.0		0.0		0.0		0.0	ns
t _{OD1}	Output buffer and pad delay, slow slew rate = off $V_{CCIO} = 3.3 \text{ V}$	C1 = 35 pF		0.4		0.6		0.7		0.9	ns
t _{OD2}	Output buffer and pad delay, slow slew rate = off V_{CCIO} = 2.5 V	C1 = 35 pF (5)		0.9		1.1		1.2		1.4	ns
t _{OD3}	Output buffer and pad delay, slow slew rate = on V _{CCIO} = 2.5 V or 3.3 V	C1 = 35 pF		5.4		5.6		5.7		5.9	ns
t _{ZX1}	Output buffer enable delay, slow slew rate = off $V_{\rm CCIO} = 3.3 \ { m V}$	C1 = 35 pF		4.0		4.0		5.0		5.0	ns
t _{ZX2}	Output buffer enable delay, slow slew rate = off V _{CCIO} = 2.5 V	C1 = 35 pF (5)		4.5		4.5		5.5		5.5	ns
t _{ZX3}	Output buffer enable delay, slow slew rate = on $V_{CCIO} = 3.3 \text{ V}$	C1 = 35 pF		9.0		9.0		10.0		10.0	ns
t_{XZ}	Output buffer disable delay	C1 = 5 pF		4.0		4.0		5.0		5.0	ns
t _{SU}	Register setup time		1.9		2.4		3.1		3.8		ns
t _H	Register hold time		1.5		2.2		3.3		4.3		ns
t _{FSU}	Register setup time of fast input		0.8		1.1		1.1		1.1		ns
t _{FH}	Register hold time of fast input		1.7		1.9		1.9		1.9		ns

Figure 13 shows the typical supply current versus frequency for MAX 7000A devices.

Figure 13. I_{CC} vs. Frequency for MAX 7000A Devices (Part 1 of 2)



EPM7128A & EPM7128AE

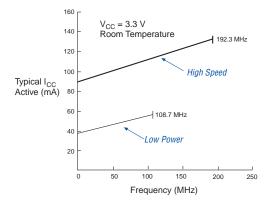
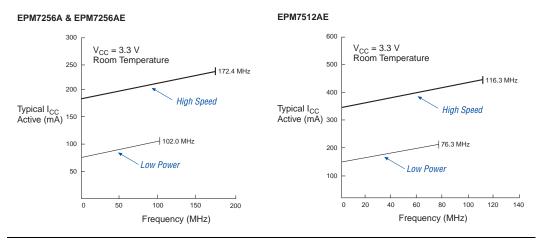


Figure 13. I_{CC} vs. Frequency for MAX 7000A Devices (Part 2 of 2)



Device Pin-Outs

See the Altera web site (http://www.altera.com) or the *Altera Digital Library* for pin-out information.

Figures 14 through 23 show the package pin-out diagrams for MAX 7000A devices.

Figure 14. 44-Pin PLCC/TQFP Package Pin-Out Diagram

Package outlines not drawn to scale.

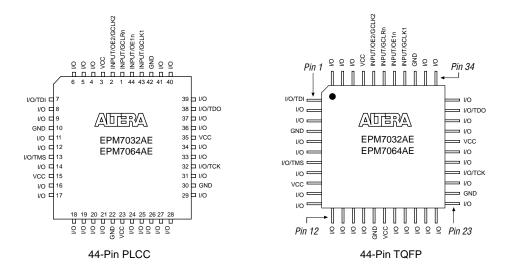


Figure 21. 208-Pin PQFP Package Pin-Out Diagram

Package outline not drawn to scale.

